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Sommario/riassunto	"This book starts with some historical notes about how AiP technology has evolved as we know it today. Then, the authors consider antennas and packages, thermal analysis and design, and measurement setups and methods for AiP technology. The authors show that the choice of antennas is usually given to those popular antennas that can be easily designed for the applications; the choice of packages is a trade-off among constraints such as electrical performance, thermo-mechanical reliability, compactness, manufacturability and cost; the choice of interconnects is governed by JEDEC for automatic assembly. Next, the book describes respectively low-temperature co-fired ceramic (LTCC), high-density interconnects (HDI), fan-out wafer level packaging (FOWLP) based AiP, and 3D-printing-based AiP. After that, the authors discuss in details the surface laminar circuit (SLC) based AiP designs for large-scale mm-wave phased arrays for 94-GHz imagers and 28-GHz 5G New Radios. Finally, the book touches on 3D AiP for sensor nodes, near-field wireless power transfer, and IoT applications"--

